

SPECIFICATIONS OF JL-D16

機型	MODEL	JL-D16
研磨盤外徑	Diameter of lapping plate	1127 mm 直徑 370 mm
夾具CARRIER (游星輪)直徑	Diameter of carrier (planetary carrier)	DP12, 200齒 DP12, Z200
夾具CARRIER (游星輪)數量	Quantity of carrier (planetary carrier)	5 SETS
每次總加工數量	Total processed quantity	6" 晶圓(Wafer): 15片(pcs) (3pc / carrier) 8" 晶圓(Wafer): 5片(pcs) (1pc / carrier) 12" 晶圓(Wafer): 5片(pcs) (1pc / carrier)
自動厚度控制	Automatic thickness control	可選配 Optional
加壓方式	Pressing method	氣壓缸加壓 Air cylinder pressing
壓力控制方式	Pressure control	電控比例閥 Electronic proportional valve
人機介面	Touchscreen	可選配 Optional
控制方式	Controller	PLC + 人機介面 PLC + Touchscreen
內齒輪轉盤	Internal gear disc	3HP
上磨盤驅動力	Upper plate drive horsepower	5HP
下磨盤驅動力	Lower plate drive horsepower	15HP
盤面轉速	Lapping plate speed	20-60 R.P.M.
磨盤壓力	Pressure on lapping plate	10-300 KG
最大加工厚度	Max. lapping thickness	40 mm
最小加工厚度	Min. lapping thickness	0.4mm
機器尺寸	Machine dimensions	W: 2300 x D: 1420 x H:2550 mm
機器重量	Machine weight	6200 kg
適用電源	Power source	3Ø 220V (3Ø 380V)

Design and specifications are subject to change without prior notice.



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JL-2022-10-1000EC



DOUBLE-SIDED LAPING / POLISHING MACHINE 雙面研磨機 / 抛光機



JL-D16

Series

機器特性 ▼

- 本機適用於平面工件之雙面同時研磨作業。具有高效率、高產能特色，適合大量生產線之精密研磨。
- 研磨後之工件具有優異的平面度、上、下面平行度及表面精度。
- 研磨機構採用游星式運轉設計，達到最佳研磨性能及研磨表面效果。
- 研磨機構可正逆轉。
- 具有5組游星輪夾具，可一次放置多工件同時研磨。
- 壓力控制方式採用電控比例閥控制，提供更穩定的輸出壓力。
- 可依客戶需求增加自動厚度控制功能(選配)。
- 本機操作控制採用PLC控制器，配合使用人機界面面板(選配)，提供操作者簡易的操控性。
- 下研磨盤轉速為無段變速，轉速範圍20~60 rpm。
- 上、下研磨盤與中心齒輪為直結式驅動，確保動作順暢，且傳動精度高。



MACHINE FEATURES ▼

- This machine is suitable for double-sided lapping operations on flat workpieces. With its high efficiency and high productivity, this machine is ideal for precision lapping in a mass production line.
- The lapping process creates outstanding flatness and parallelism between top and bottom surfaces and surface accuracy.
- The lapping mechanism running is designed with a planetary type design to achieve the optimal lapping performance and surface finish.
- The lapping mechanism is able to run clockwise and counter-clockwise.
- 5 sets of carrier (planetary carrier) allow for holding multiple workpieces for lapping simultaneously.
- An electronic proportional valve is used for pressure control, providing increased stability in pressure output.
- Upon customer request, the automatic thickness control is available (optional).
- The machine is equipped with a PLC controller in combination with the use of the touchscreen (optional), providing user-friendly operation.
- The running speed of the lower plate is variable, with a range of 20~60 RPM.
- The upper / lower plates and the center gear are driven directly, ensuring smooth motions and high transmission accuracy.

▼ 適合研磨工件種類

本機可應用於各種材質之平面工件之研磨，包括半導體材料及各種金屬、非金屬、鋁材、不鏽鋼、陶瓷等。

▼ APPLICABLE PART MATERIALS FOR LAPMING

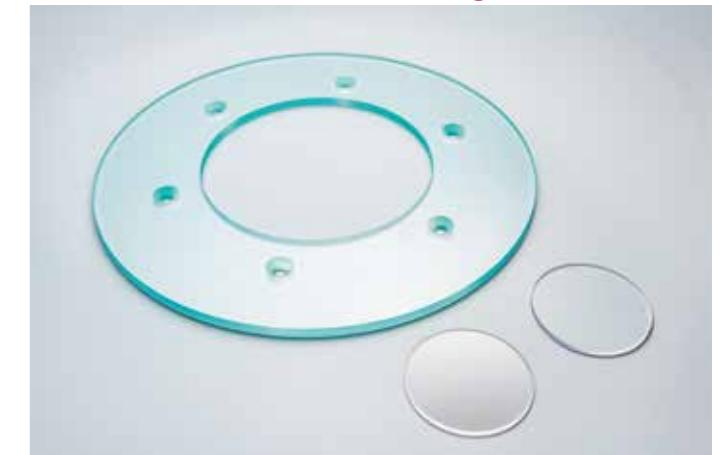
This machine is applicable for lapping various materials of flat workpiece, such as semiconductor materials and various metals, non-metals, aluminum, stainless steel, and ceramics.

研磨 Lapping



石英 Crystal

拋光 Polishing

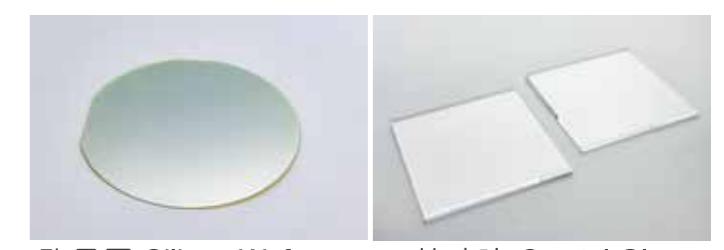


光學玻璃 Optical Glass



碳化矽 SiC

石英 Crystal



矽晶圓 Silicon Wafer

石英玻璃 Crystal Glass